

Express Mail: EV 157922336 US  
Date Deposited: 04/23/2003

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Viasystems Group Inc.	)	Atty. Dkt. No.:	8245.016
Serial No.:	09/786,787	)	Examiner:	Albert W. Paladini
Filed:	May 10, 2001	)	Group Art Unit:	2827
For:	NON-CIRCULAR MICRO VIA	)		

BOX FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following is being submitted in response to the Office Action dated October 23, 2002. Please amend the above-referenced patent application as follows:

**Listing of Claims:**

1. (Amended Herein) A wiring connection structure for a printed circuit board for interconnecting wiring circuit traces on a plurality of circuit trace layers applied on a plurality of printed circuit board layers and electrically isolated there between by the printed circuit board layers and having a printed circuit